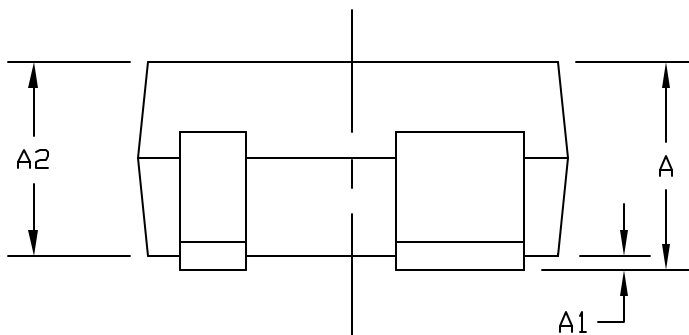


COMMON DIMENSIONS			
SYMBOL	MIN	NOM	MAX
A	0.80	0.95	1.10
A1	0.00	0.60	0.10
A2	0.80	0.90	1.00
b	0.15	0.21	0.40
b1	0.55	0.63	0.70
c	0.10	0.125	0.26
D	1.80	2.00	2.25
e	0.65 BSC.		
e1	0.50 BSC.		
E	1.15	1.25	1.35
HE	1.80	2.25	2.40
L	0.26	0.40	0.46
L1	0.425 TYP.		
Q1	0.10	0.30	0.40
PKG. CODE	X4-1		

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS ARE INCLUSIVE OF PLATING.
3. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH & METAL BURR.
4. COPLANARITY 4 MILS. MAX.
5. FOOT LENGTH MEASURED AT INTERCEPT POINT BETWEEN DATUM "A" AND LEAD SURFACE.
6. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
7. LEAD CENTERLINES TO BE AT TRUE POSITION AS DEFINED BY BASIC DIMENSION "e" AND "e1", ± 0.05 .
8. ALL SPECIFICATIONS COMPLY TO JEITA SC-70 EXCEPT b1, e1 AND L DIMENSIONS.



-DRAWING NOT TO SCALE-

DALLAS SEMICONDUCTOR **MAXIM**

TITLE:
PACKAGE OUTLINE, 4L SC70

APPROVAL	DOCUMENT CONTROL NO. 21-0098	REV. E	1/1
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